



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-11-20
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	AKPK*6TAPY23	A	CA2A	2013-11-20
Amount	UoM	Unit type	ST ECOPACK Grade	
0.80	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Gold (Au)	Nickel (Ni)		

Package Designator	Size	Nbr of instances	Shape	
CHP	NAC	8	No lead	
Comment	Package: SOD882T - 1x0.6x0.4 2LDS; MDF valid for ESDALC5-1BT2Y			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AKPK*6TAPY23					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.272	mg	supplier	die	Silicon (Si)	7440-21-3		0.27	mg	992647	337500
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	3676	1250
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.001	mg	3676	1250
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.005	mg	1000000	6250
Die attach	Other inorganic materials	0.021	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.018	mg	857143	22500
Die attach				supplier	glue or tape	Amine Polymer	28630-26-4		0.002	mg	95238	2500
Die attach				supplier	glue or tape	epoxy resin	Proprietary		0.001	mg	47619	1250
Bonding wire	Precious metals	0.012	mg	supplier	wire	Gold (Au)	7440-57-5		0.012	mg	1000000	15000
encapsulation	Other inorganic materials	0.49	mg	supplier	mold compound	silica vitreous	60676-86-0		0.43	mg	877551	537500
encapsulation				supplier	mold compound	Phenolic resin	Proprietary		0.023	mg	46939	28750
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.018	mg	36735	22500
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.001	mg	2041	1250
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.018	mg	36735	22500